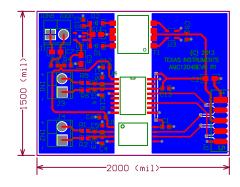
Texas Instruments, Inc. 12500 TI Blvd., Dallas, TX 75243					
AMC1204EVM				Engs	Hendrick Hendrick
REV: 1	SCALE: 1.00	Date:	04MAR08		
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○ 6 45mil □ 29 15mil 35 Total

Notes:

1. BOARD MATERIAL

Base laminate material to be NEMA GRADE: FR4 or FR5. Natural color and UL rated 105 Degree C, 94V-0. Finished board thickness to be 0.062 (+/- .010).

2. SOLDER MASK

Solder masks shall be applied over bare copper with materials in accordance with IPC-SM-840 and the registration shall be .010 of the circumscribed land patterns. Material: Wet Film/Dry Film/Photo Imagable. If fabrication process does not allow soldermask over bare copper, dry film over solder plating shall be used.

3. SILKSCREENING

Silk-screening shall be applied to the board with permanent non-conductive white epoxy ink. The silk-screens shall be legible, defined, and registered to the board with a tolerance of +/- .020 mils.

5. DRILLING

Tooling holes shall be first drilled and free of plating. Non-critical unplated holes may be drilled in the second drilling operation, but plating shall not be allowed inside the barrels. Diameters in drill table (*.GD1) are after plating.

6. ETCHING

Etching tolerance for all layers shall be $\pm -10\%$ of original artwork pattern. This tolerance shall be adjusted to $\pm -10\%$ if the artwork pattern contains trace widths of less than 10 mils, or surface mount land patterns of less than .050 inch pitch.

7. SOLDER PLATING

All unmasked conductive copper areas shall be coated with a minimum of .001 inches of 60/40 solder and shall be finished by hot air/oil leveling or hydro squeegee method. Land patterns shall be smooth and evenly coated.

8. COPPER REQUIRMENTS

Starting copper weights shall be as follows: Outer signal layers: 1 oz. Inner signal layers: 1 oz.

9. BOARD DIMENSIONS

2.000 inches X .725 inches

1.143mm PTH 0.381mm PTH